# Special Issue

# Metallization of Non-Conductive Substrates

### Message from the Guest Editor

This Special Issue aims to highlight recent advancement in the science and technology associated with metallization of non-conductive substrates. Metallization of non-conductive substrates plays an important role in various application fields including microelectronics and optoelectronics. In some specific applications, such as flexible electronics, metallization of polymeric substrates especially attracts more attention. Vacuum-based deposition method can grow a uniform and adhesive metal or alloy film on non-conductive substrates but expensive facilities are always a big concern. Solution-based deposition method is rather simple and cost-effective but an improvement of the film uniformity and adhesion requires more research works. In this special issue, substrates of interests include, but are not limited to, polymer, glass, ceramic, and silicon. Specific topic areas for manuscript submissions include, but are not limited to, methodology of physical and chemical deposition, structures and properties of deposits, new catalysts and deposition methods, metals and alloys deposition, and adhesion and interfacial properties.

### Guest Editor

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### Deadline for manuscript submissions

closed (31 December 2017)

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# About the Journal

## Message from the Editorial Board

Metallic materials play a vital role in the economic life of modern societies; contributions are sought on fresh developments that enhance our understanding of the fundamental aspects related to the relationships between processing, properties and microstructure – disciplines in the metallurgical field ranging from processing, mechanical behavior, phase transitions and microstructural evolution, nanostructures, as well as unique metallic properties – inspire general and scholarly interest among the scientific community.

## Editors-in-Chief

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